imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





00432





Surface Mount Gaskets and Grounding Pads

Our SMG gaskets can be used with many different types of board level shielding needs and when grounding points are required on your board. Form-in-Place gaskets can be eliminated by transferring the gasket to the board rather than to the thin edge of a casting or machined housing. No fear of damaging a thin Form-in-Place gasket during handling and assembly process. High speed SMT assembly of our tape and reel supplied gaskets make this a low cost reliable assembly option.

Part Numbers	Sizes						Packaging	Core Materials	Cross Section
Full Nullibers	Height		Width		Length		(parts per reel)		(not to scale)
SMG098118R-0.098	0.098	2.5	0.118	3	0.098	2.5	2100	Hollow High Temp. Sil. Sponge	8
SMG118118R-0.079	0.118	3	0.118	3	0.079	2	1800	Hollow High Temp. Sil. Sponge	Q
SMG118118R-0.118	0.118	3	0.118	3	0.118	3	1800	Solid High Temp. Foam	0
SMG118157R-0.197	0.118	3	0.157	4	0.197	5	1800	Hollow High Temp. Sil. Sponge	A
SMG118197R-0.256	0.118	3	0.197	5	0.256	7	1500	Solid High Temp. Foam	
SMG256197R-0.118	0.256	6.5	0.197	5	0.118	3	1100	Solid High Temp. Foam	
SMG157256R-0.276	0.157	4	0.256	6.5	0.276	7	1200	Hollow High Temp. Sil. Sponge	6
SMG236295R-0.157	0.236	6	0.295	7.5	0.157	4	1200	Hollow High Temp. Sil. Sponge	B
SMG236354R-0.315	0.236	6	0.354	9	0.315	8	600	Hollow High Temp. Sil. Sponge	8
SMG295197R-0.138	0.295	7.5	0.197	5	0.138	3.5	1000	Hollow High Temp. Sil. Sponge	X

Black = inches Blue = mm Tolerance: +/- .019" (.48mm)



Global EMI Shielding Technology Center 12420 Race Track Rd., Tampa, Florida 33626 866.TECH.EMI (866.832.4364) t 813.855.6921 f 813.855.3291

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Applications

- Mobile Electronics
- Computers
- Integrated Circuits

Benefits

- Low Cost
- Suitable for Automated Placement
- Tape & Reel Packaging
- Off-The-Shelf
- Reflow Capabilities
- Low Compression Requirements
- Resilient

Material

- Outer Wrap
- Polyimide coated Sn/Cu





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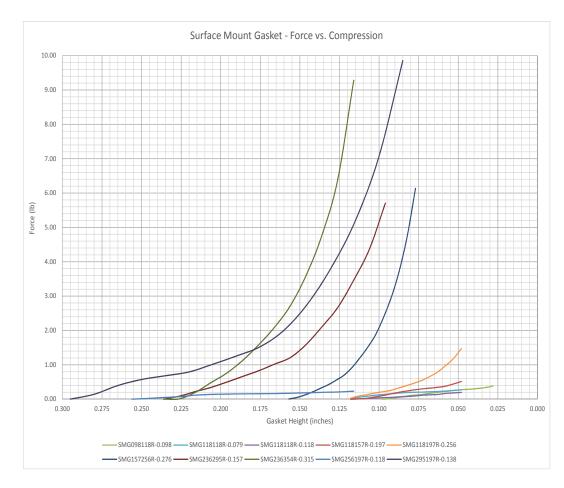


Product Profile

00432

Surface Mount Gaskets and Grounding Pads

Property		Method	Silicone Sponge	Polyurethane Foam
Outer Material		-	Polyimide coated Sn/Cu	Polyimide coated Sn/Cu
Color		-	Silver	Silver
Surface Resistance		ASTM D257	< 0.05 Ohm/in ²	< 0.05 Ohm/in²
Hardness of Silicone		ASTM D2240	60 (Shore A)	20 (Shore C)
Deformation %	ASTM D5947	260°C, 30min	≤ 10%	≤ 10%
Resilience Ratio	ASTM D374	150°C, 100hrs, 20% compression	≥ 95%	≥ 85%
	ASTM D374	-40°C, 100hrs, 20% compression		
	ASTM D374	85°C, 85% Rel. Humidity, 100hrs, 20% compression	≥ 95%	≥ 95%
	ASTM D374	300 cycles, 20% compression		



Applications

a HEICO company

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